



Hydrosoluble Flux

FLUX TYPE H32M

H32M Flux is a mild hydrosoluble flux for use in flow soldering equipment for the production of printed circuit boards. It is also effective for tinning the ends of copper multi-stranded wire. This mild hydrosoluble flux is more effective than rosin based flux in removing oxides from the surfaces to be soldered particularly in the case of bare copper.

- Non rosinous, organic acid, activated flux soluble in water or alcohol
- Equivalent to rosin RMA type flux
- Meets standards NFC 90550, Din 8511 and 8516

Physiochemical Characteristics

- Solution : Alcoholised
- Colouration : Clear
- Density at 20°C : 0.920 +/- 0.3 at 20C
- Water washing : Highly soluble
- Alcohol washing : Very soluble
- Flash point : 21°C
- Chlorine rate : 0.05%
- Acidity : IA = 65

Application Notes:

H32M can be used for foam or spray fluxing in all types of automatic flow soldering machines. Due to its concentration, the flux assists in reducing the formation of icicles, craters and facilitates good capillary rise in metallized holes.

Preheat temperature after fluxing should be between 80° and 90°C to give good levels of activation.

H32M residue must be removed after soldering by washing in either water or alcohol base cleaning materials.

Maintenance of the flux density is achieved by adding dilutant D305 to within the limits of SPG. 0.890 to 0.950.

Health and Safety:

Use in a well ventilated area away from sources of flame or ignition (COSH sheet available)

Packaging:

Throwaway 10 litre HDPE containers.

Storage:

In original hermetically sealed containers, stored at an ideal temperature of around 20°C, for a 12 month period.